



Covalent Materials Corporation

Nissei Bldg., 6-3, Osaki 1-chome, Shinagawa-ku,
Tokyo 141-0032, Japan

February 18, 2015

**Notice of Completion of Early Redemption of
1st Series of Unsecured Bonds (with inter-bond *pari passu* clause)**

Covalent Materials Corporation (the “Company”) hereby announces that with respect to the 1st Series of Unsecured Bonds (with inter-bond *pari passu* clause) (ISIN Code: JP330135A829) issued by the Company on February 18, 2008 (the “Bonds”), the Company has completely redeemed all outstanding amounts on the Bonds as of February 18, 2015, as the Company notified that it would do in the “Notice regarding an Early Redemption of Entire Amount and Occurrence of Redemption Option Event of the 1st Series of Unsecured Bonds (with Inter-Bond *Pari Passu* Clause),” dated December 26, 2014.

Toshio Nagahama
Representative Director, President and CEO
Covalent Materials Corporation
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